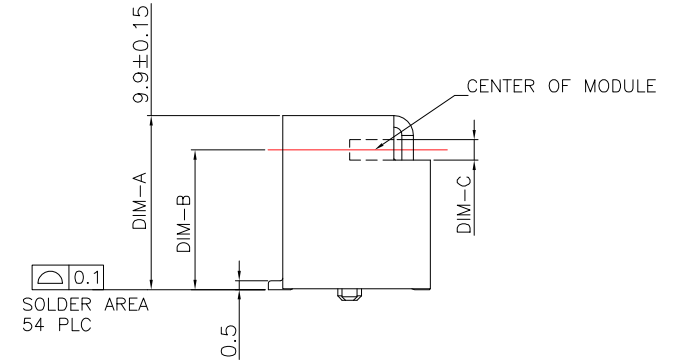
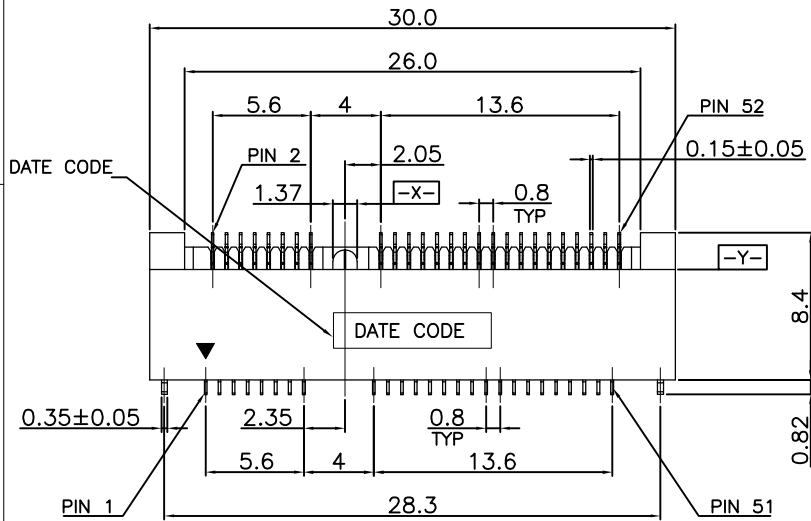




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SPECIFICATION:

1. ELECTRICAL

- 1.1 Current Rating: 0.5A per pin
- 1.2 Voltage Rating: 50V DC
- 1.3 Contact Resistance: 5 5mΩ Max
- 1.4 Insulation Resistance: 500MΩ Min
- 1.5 Dielectric Withstanding Voltage: 300VAC

2. MECHANICAL

- 2.1 Durability: 100 Cycle
- 2.2 Insertion Force: 2.3Kgf max.
- 2.3 Extraction Force: 2.3Kgf max.

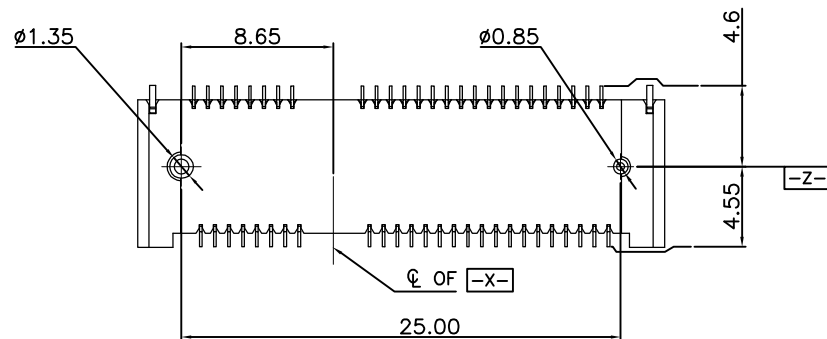
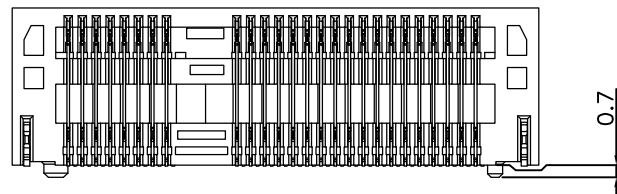
3. ENVIRONMENTAL

- 3.1 Operating temperature range: -40 °C~+85°C
- 3.2 Storage temperature range: -40 °C~+85°C

4. SOLDER ABILITY

- 4.1 Recommended IR Reflow Temperature: 260 °C 10Sec

LTEM NO	DIM-A	DIM-B	DIM-C
PCI-E-H40-52P	4.0mm	2.05mm	1.12mm
PCI-E-H52-52P	5.2mm	3.25mm	1.12mm
PCI-E-H56-52P	5.6mm	3.65mm	1.12mm
PCI-E-H70-52P	7.0mm	5.05mm	1.12mm
PCI-E-H80-52P	8.0mm	6.05mm	1.16mm
PCI-E-H90-52P	9.0mm	7.05mm	1.16mm
PCI-E-H99-52P	9.9mm	7.95mm	1.16mm



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.35	X :±2°
X.X :±0.25	X.X :±1°
X.XX :±0.15	



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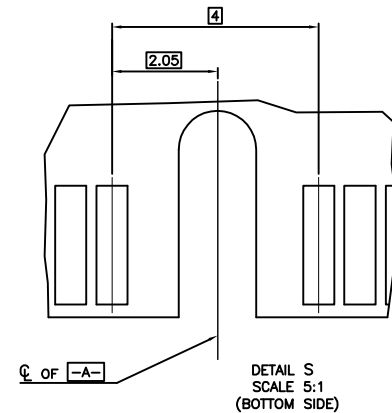
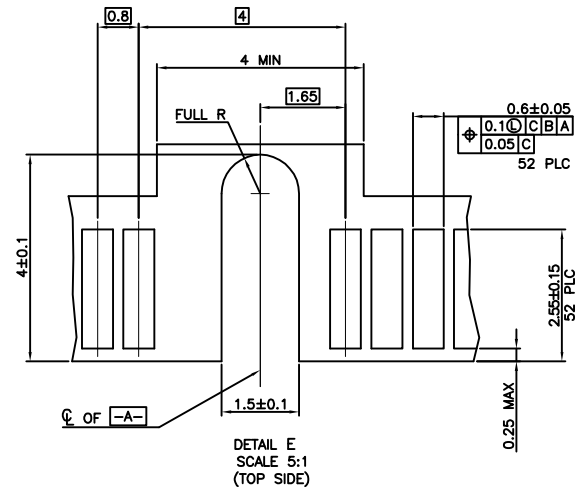
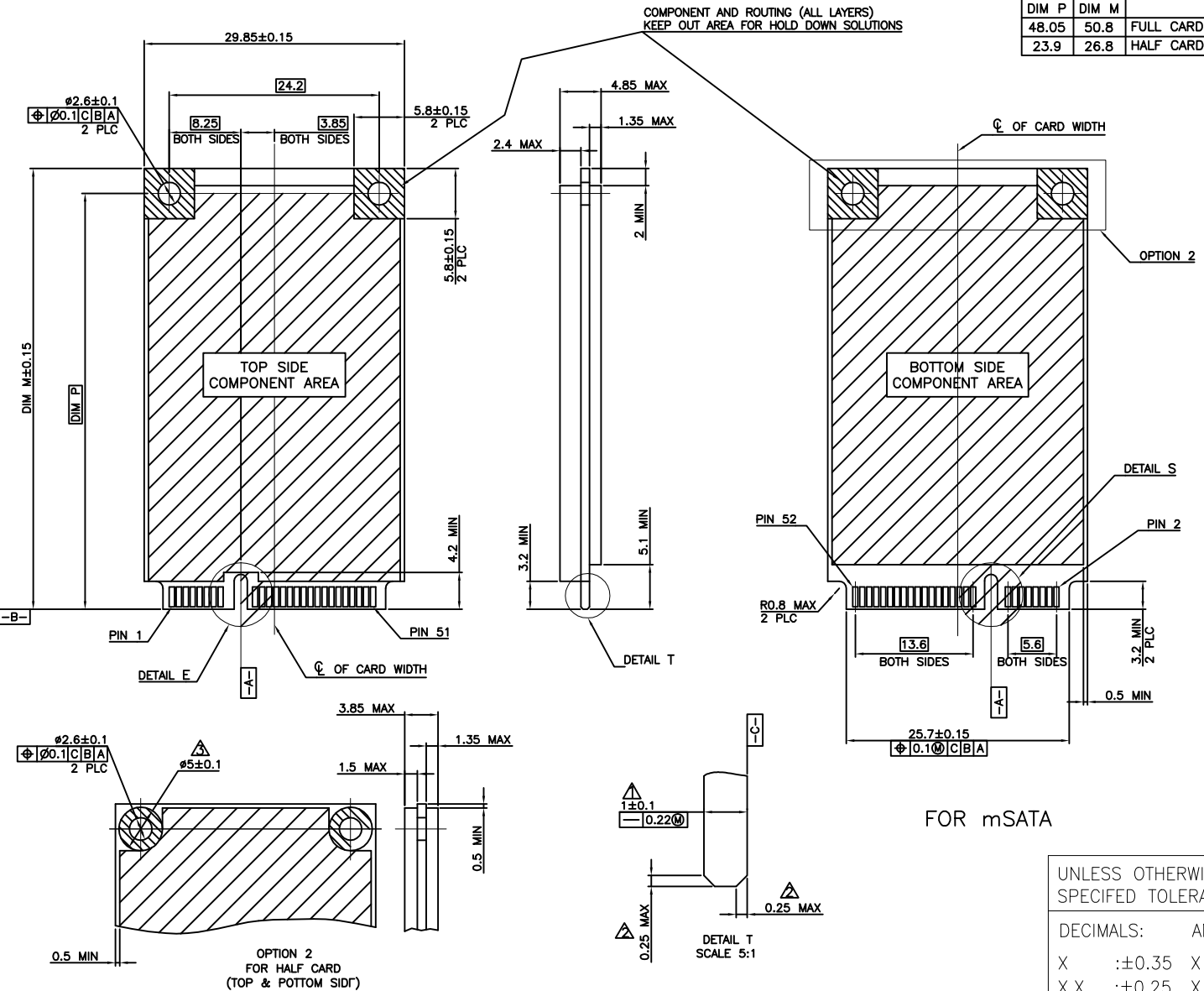
TITLE	MINI PCI EXPRESS			
DWN	xiong	PART NO. PCI-E-HXX-52PIN		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:1OF 1	

CUSTOMER COPY



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

A
B
C
D



NOTES:

- ▲ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
- ▲ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING BURRS FROM PCB AND CONTACT MATERIALS.
- ▲ COMPONENT AND ROUTING (TOP/BOTTOM LAYER) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS.

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:
X :±0.35 X :±2°
X.X :±0.25 X.X :±1°
X.XX :±0.15

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1 2 3 4 5 6